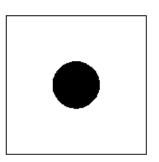
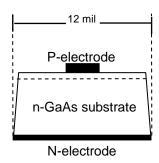
# EPISTAR

#### > Mechanical Specification:

- (1) Dimension
  - Chip size: 12 mil x 12 mil (305±25 μm x 305±25 μm)
  - Thickness: 6.7 mil (170±25 μm)
  - P bonding pad: 4.6 mil (117 $\pm$ 10  $\mu$ m)
- (2) Metallization
  - Topside P electrode: Au alloy
  - Backside N electrode: Au alloy





#### Features:

- High luminous intensity
- $\cdot$  ITO layer on top

#### **Applications:**

- · Outdoor display
- Traffic signal

# > Electro-optical Characteristics at 25°C:

Parameter	Symbol		Condition	Min.	Тур.	Max.	Unit
Family of Maltana	Vf1		lf = 10μΑ	1.35	-	-	V
Forward Voltage	Vf2		lf = 20mA	-	2.0	2.4	V
Reverse Current	lr		Vr = 10V	-	-	10	μΑ
Peak Wavelength	λρ		lf = 20mA	-	591	-	nm
Dominant Wavelength <sup>(1)</sup>	λd		lf = 20mA	584	589	594	nm
Spectra Half-width	Δλ		lf = 20mA	-	15	-	nm
Luminous Intensity <sup>(2)(3)</sup>		E <b>7</b>	lf = 20mA	110	-	-	mcd
	lv	E8		140	-	-	
		E9		170	-	-	
		E10		200	-	-	
		E11		250	-	-	

#### Note:

(1) Basically, the wavelength span is 10nm; however, customers' special requirements are also welcome.

(2) Customers' special requirements are also welcome.

(3) Luminous intensity is measured by EPISTAR's equipment on bare chips.

This product is made and sold under one or more of the following patents: Taiwan Patent Certificate Nos.: 098998; 113696; 128153; 131010; 144415; 148677; 170789; 183481; 183846; U.S. Patent Nos.: 5,008,718; 5,164,798; 5,233,204; 5,789,768; 6,078,064; 6,057,562; 6,225,648; 6,552,367; 6,876,005, and any foreign counterparts.

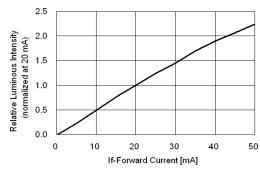
Parameter	Symbol	Condition	Rating	Unit
Forward DC Current	If	Ta = 25°C	≤ 50	mA
Reverse Voltage	Vr	Ta = 25°C	≤ 10	V
Junction Temperature	Tj	-	≤ 115	°C
		Chip	-40 ~ +85	°C
Storage Temperature	Tstg	Chip-on-tape/storage	5 ~ 35	°C
		Chip-on-tape/transportation	-20 ~ +65	°C
Temperature during Packaging	-	-	280(<10sec)	°C

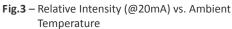
## > Absolute Maximum Ratings:

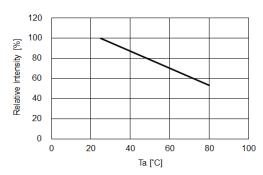
Note: Maximum ratings are package dependent. The above maximum ratings were determined using a Printed Circuit Board (PCB) without an encapsulant. Stresses in excess of the absolute maximum ratings such as forward current and junction temperature may cause damage to the LED

### > Characteristic Curves:











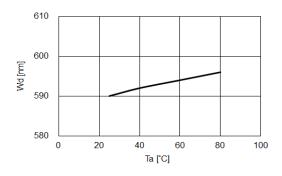


Fig.2 – Forward Current vs. Forward Voltage

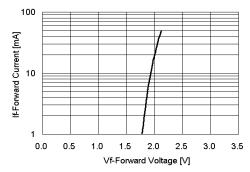


Fig.4 – Forward Voltage (@20mA) vs. Ambient Temperature

